



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20160408001
Qualification of Additional Fab (RFAB) and Additional Assembly/Test (TI Clark) sites
for Select Devices
Change Notification / Sample Request

Date: 4/12/2016
To: Newark/Farnell PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

20160408001
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TLV320AIC3106IRGZT	null
TLV320AIC3106IRGZR	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20160408001		PCN Date:	4/12/2016																	
Title:	Qualification of Additional Fab (RFAB) and Additional Assembly/Test (TI Clark) sites for Select Devices																				
Customer Contact:	PCN Manager		Dept:	Quality Services																	
Proposed 1st Ship Date:	7/12/2016		Estimated Sample Availability:	Provided upon Request																	
Change Type:																					
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Assembly Materials																
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification																
<input checked="" type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process																
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process																
<input checked="" type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process																
		<input type="checkbox"/>	Part number change																		
PCN Details																					
Description of Change:																					
Texas Instruments is pleased to announce the qualification of RFAB as an additional fab site and TI Clark as an additional assembly/test site for the devices listed below. Device construction differences between the various sites are as follows:																					
<table border="1"> <thead> <tr> <th>What (Package Designator)</th> <th>MLA</th> <th>CRS</th> <th>TI Clark</th> </tr> </thead> <tbody> <tr> <td>Mount Compound (RHB)</td> <td>4205846</td> <td>SID#435143</td> <td>4207768</td> </tr> <tr> <td>Mount Compound (RGZ)</td> <td>n/a</td> <td>SID#435143</td> <td>4207123</td> </tr> </tbody> </table>						What (Package Designator)	MLA	CRS	TI Clark	Mount Compound (RHB)	4205846	SID#435143	4207768	Mount Compound (RGZ)	n/a	SID#435143	4207123				
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Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter																
DP1DM5	C05	200 mm	RFAB	C05	300 mm																
Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.																					
Reason for Change:																					
Continuity of Supply																					
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):																					
None																					
Anticipated impact on Material Declaration																					
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI ECO website .																		
Changes to product identification resulting from this PCN:																					
<table border="1"> <thead> <tr> <th>Assembly Site</th> <th>Assembly Site Origin (22L)</th> <th>Assembly Country Code (21L)</th> <th>Assembly City</th> </tr> </thead> <tbody> <tr> <td>TI Malaysia</td> <td>MLA</td> <td>MYS</td> <td>Kuala Lumpur</td> </tr> <tr> <td>Carsem</td> <td>CRS</td> <td>MYS</td> <td>Jelapang</td> </tr> <tr> <td>TI Clark</td> <td>QAB</td> <td>PHL</td> <td>Angeles City</td> </tr> </tbody> </table>						Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (21L)	Assembly City	TI Malaysia	MLA	MYS	Kuala Lumpur	Carsem	CRS	MYS	Jelapang	TI Clark	QAB	PHL	Angeles City
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TI Malaysia	MLA	MYS	Kuala Lumpur																		
Carsem	CRS	MYS	Jelapang																		
TI Clark	QAB	PHL	Angeles City																		

Fab Sites

Chip Sites	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
DP1DM5	DM5	USA	Dallas

New

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
RFAB	RFB	USA	Richardson

Sample product shipping label (not actual product label)

TEXAS INSTRUMENTS
 MADE IN: Malaysia
 2DC: 2Q:
 MSL 2 /260C/1 YEAR SEAL DT
 MSL 1 /235C/UNLIM 03/29/04
 OPT: 39
 ITEM:
LBL: 5A (L)T0:1750

(1P) SN74LS07NSR
 (Q) 2000 (D) 0336
 (31T) LOT: 3959047MLA
 (4W) TKY (1T) 7523483SI2
 (P)
 (2P) REV: (V) 0033317
 (20L) CS0: SHE (21L) CCO: USA
 (22L) ASO: MLA (23L) ACO: MYS

Topside Device marking:

Assembly site code for MLA= K
 Assembly site code for CRS = W

Assembly site code for QAB = I

Product Affected

TLV320AIC3004IRHBR	TLV320AIC3105IRHBR	TLV320AIC3106IRGZR	TLVAIC3105IRHBRG4
TLV320AIC3004IRHBT	TLV320AIC3105IRHBT	TLV320AIC3106IRGZT	



TI Information
Selective Disclosure

Qualification Report

TLV320AIC3106/5/6RGZ in RFAB and Clark (release the G2TIAIC39A die in Clark)

Approve Date 05-Apr-2016

Product Attributes

Attributes	Qual Device: TLV320AIC3106IRGZR	QBS Process Reference: VSP6825BZRC	QBS Package Reference: SN65LVCP40RGZ	QBS Package Reference: TPS62402DRCR _CU_WIRE
Assembly Site	CLARK-AT	PHI	CLARK-AT	CLARK-AT
Package Family	QFN	JRBGA	QFN	SON
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	RFAB	HIJI, RFAB	FFAB	FFAB
Wafer Process	1118C05	1833C05, LBC4	BICOM3	3370A12

- QBS: Qual By Similarity
 - Qual Device TLV320AIC3106IRGZR is qualified at LEVEL2-260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TLV320AIC3106IRGZR	QBS Process Reference: VSP6825BZRC	QBS Package Reference: SN65LVCP40RGZ	QBS Package Reference: TPS62402DRCR _CU_WIRE
AC	Autoclave 121C	96 Hours	-	-	1/77/0	1/77/0
ED	Electrical Characterization	Per Datasheet Parameters	Pass	-	-	-
HAST	Biased HAST,130C/85%RH	96 Hours	-	3/230/0	1/77/0	-
HTOL	Life Test, 140C	480 Hours	-	3/231/0	-	-
HTOL	Life Test, 155C	240 Hours	-	-	1/77/0	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	3/231/0	1/77/0	1/77/0
PD	Physical Dimensions	--	-	-	1/5/0	1/5/0
TC	Temperature Cycle, -65/150C	500 Cycles	-	3/231/0	1/77/0	1/77/0
TS	Thermal Shock, -65/150C	500 Cycles	-	-	-	1/77/0
WBP	Bond Pull	Wires	1/76/0	-	1/76/0	1/76/0
WBS	Wire Bond Shear	Wires	1/76/0	-	1/76/0	1/76/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com